

Product/ Process Change Notification

Froducti Frocess Change Nothication					
1. PCN No.:		QPCN12025			
2. Subject:		Bonding wire material change at SOD-523 (Switching, Zener & SKY) SMD Diode			
3. To:		Refer to involved customer list			
4. Issued by:		Owen Wang			
5. Issue date:		3-Dec-2012			
6. Proposed first ship date for change:		4-Mar-2013			
7. Affected Product Identification					
Switching Diode & Array, Zener Diode & Array, and Schottky Diode & Array, SOD-523 package More details please see TSC involved P/N list.					
8. Change Description : (OLD Vs. NE	w Com				
Old:		New:			
➤ Gold bonding wire.		Copper bonding wire.			
9. Reason for Change:					
Follow the trend of common process in the market.					
10. Anticipated Impact: (form, fit, function	on, qual	ity or reliability)			
1. Product outline: N	o chang				
_	Bonding wire material change				
•	No change				
	No change No change				
	o change o change				
	y date c				
11. Qualification plan/result:					
Comparison report see attached PPAP is available on demand					
12. Sample availability Date:		3-Dec-2012			
13. Tentative implementation date:		3-Jan-2013			
14. Remarks					
15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)		3-Jan-2013			
16. Approved by:		Quayer Chen			



Product/ Process Change Notification Customer Approval Form_ QPCN12025

(Please tick the field what is valid for you!)							
	We agree with this proposed change and its schedule.						
	We have object	tions					
	We need more	information:					
	We need more	mormation.					
	We need samp	le:					
Con	npany:						
Nan	ne:						
Add	Iress:						
Sigi	nature:		Date:				